

CIRCUIT ENCAPSULATION

Abstract

A circuit on a circuit board is encapsulated using a first mold section and a second mold section. The first mold section closes on one side of the board, and the first mold section has an exposed first conduit. The second mold section closes on another side of the board, and the second mold section has a second conduit for pushing molding compound into a mold cavity in at least one of the mold sections. The second conduit has a side opened to the first mold section when the first and second mold sections are closed on the circuit board. A piston extends through the first conduit to close the side of the second conduit.

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